DATA SHEET



PHOTOCOUPLER PS8101

1 Mbps HIGH CMR ANALOG OUTPUT TYPE 5-PIN SOP PHOTOCOUPLER

-NEPOC Series-

DESCRIPTION

The PS8101 is an optically coupled isolator containing a GaAlAs LED on the light emitting diode (input side) and a PIN photodiode and a high-speed amplifier transistor on the output side on one chip.

This is a plastic SOP (Small Out-line Package) type for high density applications.

FEATURES

- Wave soldering (260°C, 10 s, One)
- High common mode transient immunity (CMH, CML = $\pm 10 \text{ kV/}\mu\text{s MIN.}$)
- High supply voltage (Vcc = 35 V)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- High-speed response (tphL = 0.8 μ s MAX., tpLH = 1.2 μ s MAX.)
- Ordering number of taping product: PS8101-F3, F4: 2 500 pcs/reel

APPLICATIONS

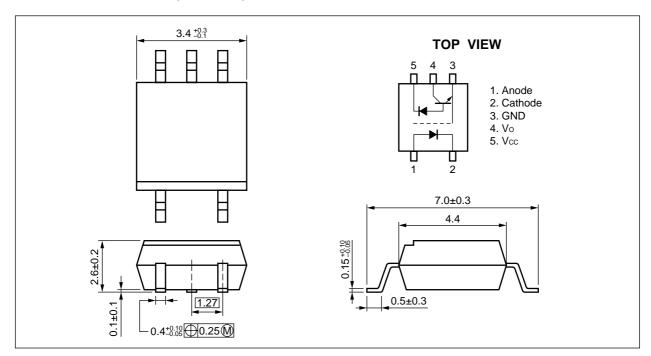
- · Computer and peripheral manufactures
- · General purpose inverter
- Substitutions for relays and pulse transformers
- · Power supply

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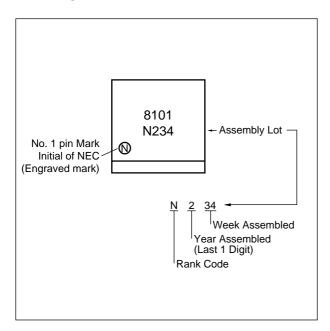
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.



PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE





ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS8101	5-pin SOP	20 pcs (Tape 20 pcs cut)	PS8101
PS8101-F3		Embossed Tape 2 500 pcs/reel	
PS8101-F4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current	lF	25	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation 1	Po	45	mW	
Detector	Supply Voltage	Vcc	35	V	
	Output Voltage	Vo	35	V	
	Output Current	lo	8.0	mA	
	Power Dissipation 2	Pc	100	mW	
Isolation Voltage ^{*3}		BV	2 500	Vr.m.s.	
Operating Ambient Temperature		TA	-55 to +100	°C	
Storage Temperature		T _{stg}	-55 to +125	°C	

^{*1} Reduced to 0.45 mW/ $^{\circ}$ C at T_A = 25 $^{\circ}$ C or more.

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^{*2} Reduced to 1.00 mW/ $^{\circ}$ C at T_A = 25 $^{\circ}$ C or more.

^{*3} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output.



ELECTRICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 16 mA		1.7	2.2	V
	Reverse Current	lr	VR = 3 V			10	μΑ
	Forward Voltage Temperature Coefficient	$\Delta V_F/\Delta T$	I _F = 16 mA		-2.1		mV/°C
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Current	Іон (1)	IF = 0 mA, Vcc = Vo = 5.5 V		3	500	nA
	High Level Output Current	Іон (2)	IF = 0 mA, Vcc = Vo = 30 V			100	μА
	Low Level Output Voltage	Vol	IF = 16 mA, Vcc = 4.5 V, Io = 1.2 mA		0.1	0.4	V
	Low Level Supply Current	Iccl	IF = 16 mA, Vo = open, Vcc = 30 V		50		μΑ
	High Level Supply Current	Іссн	IF = 0 mA, Vo = open, Vcc = 30 V		0.01	2	
Coupled	Current Transfer Ratio 1	CTR	IF = 16 mA, Vcc = 4.5 V, Vo = 0.4 V	15	20	35	%
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , RH = 40 to 60 %	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Propagation Delay Time $(H \rightarrow L)^2$	tрнL	IF = 16 mA, Vcc = 5 V, RL = 2.2 k Ω , CL = 15 pF		0.5	0.8	μs
	Propagation Delay Time (L → H) ²	tрцн			0.6	1.2	
	Common Mode Transient Immunity at High Level Output ³	Смн	IF = 0 mA, Vcc = 5 V, RL = 4.1 k Ω , VcM = 1.5 kV	10			kV/μs
	Common Mode Transient Immunity at Low Level Output ¹³	Смь	$I_F = 16 \text{ mA}, \text{ Vcc} = 5 \text{ V}, \text{ RL} = 4.1 \text{ k}\Omega, \\ \text{VcM} = 1.5 \text{ kV}$	-10			

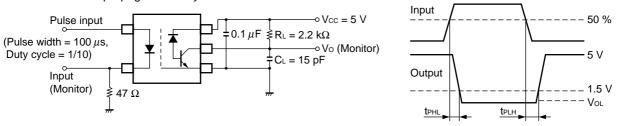
*1 CTR rank

K: 20 to 35 (%) N: 15 to 35 (%)

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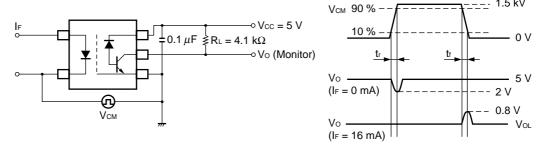


*2 Test circuit for propagation delay time



C_L is approximately 15 pF which includes probe and stray wiring capacitance

*3 Test circuit for common mode transient immunity

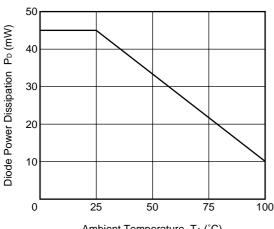


USAGE CAUTIONS

- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of 0.1 μ F is used between Vcc and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.

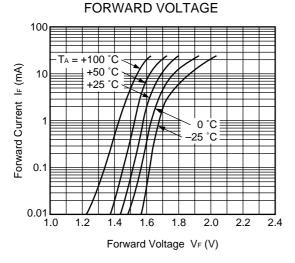
TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE

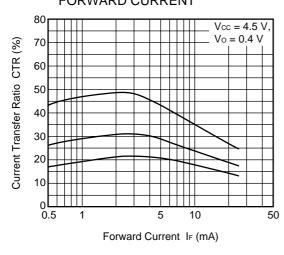


Ambient Temperature T_A (°C)

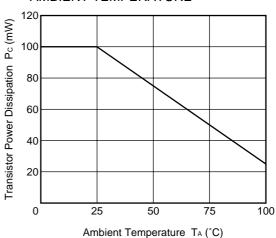
FORWARD CURRENT vs.



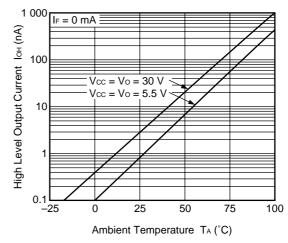
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



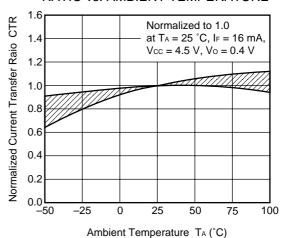
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE

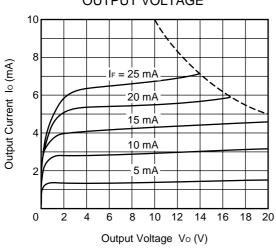


NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE

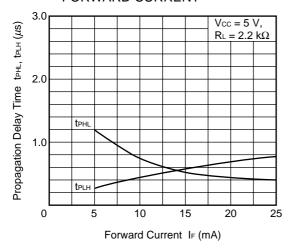




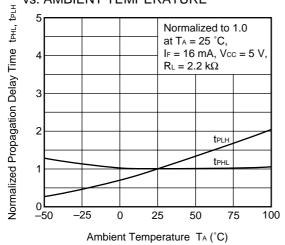
OUTPUT CURRENT vs. OUTPUT VOLTAGE



PROPAGATION DELAY TIME vs. FORWARD CURRENT

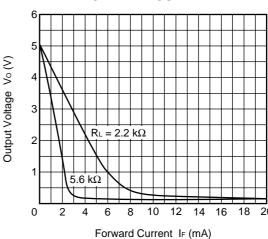


NORMALIZED PROPAGATION DELAY TIME vs. AMBIENT TEMPERATURE

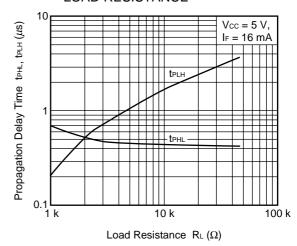


Remark The graphs indicate nominal characteristics.

OUTPUT VOLTAGE vs. FORWARD CURRENT

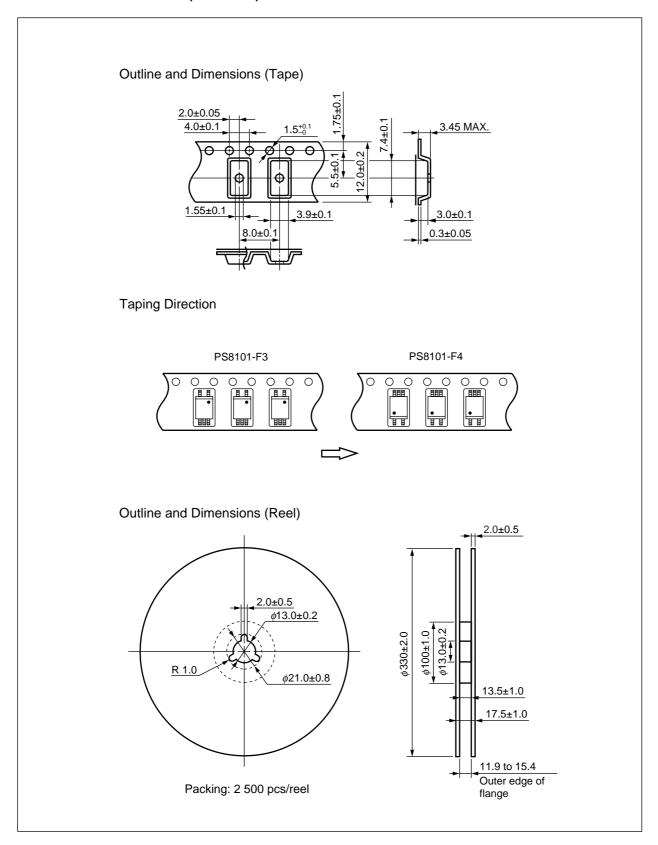


PROPAGATION DELAY TIME vs. LOAD RESISTANCE





TAPING SPECIFICATIONS (UNIT: mm)





NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

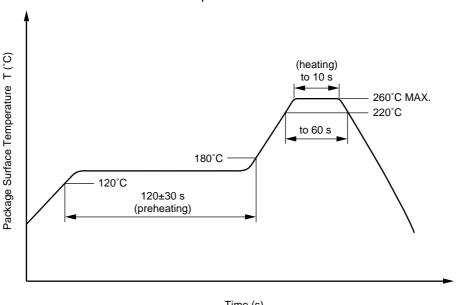
• Time of peak reflow temperature 10 seconds or less 60 seconds or less • Time of temperature higher than 220°C

• Time to preheat temperature from 120 to 180°C 120±30 s Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

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M8E 00.4-0110



SAFETY INFORMATION ON THIS PRODUCT

Caution

GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

▶For further information, please contact

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